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PCN # 248
Final Notification Date:
February 13, 2025

Product / Process Change Notice

Part Affected:

All devices manufactured in the TO-72 case.

Extent of Change:

Additional assembly location.

Reason for Change:

As part of Central Semiconductor’s supply chain risk mitigation initiative, and in an effort to ensure an uninterrupted supply of product, an additional assembly location is being added for the referenced product. Device specifications, quality, and reliability are not impacted by this addition.

Effect of Change:

This addition does not affect the fit, form or function of the device.

Qualification:

No.	Test	Conditions (Reference standards are in bold)	Qty	Pass/Fail	Test Results
1	Device Life Tests				
A	High Temperature Reverse Bias (HTRB)	T=125°C, t = 1000 hours Bias Conditions per Device Datasheet JESD22-A108	77	Pass	77/77
B	High Temperature Storage Life (HTSL)	T=150°C, t = 1000 hours JESD22-A103	77	Pass	77/77
C	Thermal Shock	100 cycles, dwell time = 5 min, -65°C to +150°C, max transfer time = 20s JESD22-A106	77	Pass	77/77
D	Temperature Cycling (TC)	-65°C to +150°C, T _{dwell} = 15min, 1000 cycles MIL-STD-750 TM1051	77	Pass	77/77
E	Resistance To Solder Shock	Pb free: T =270°C ±5°C, Dwell=7s +2/-0 Thru-hole devices submerge to case, JESD22-B106	5	Pass	5/5
F	Solderability	Steam Age: T=93°C +3/-5°C. Pb-free Dip: T=245°C +/-5°C, Dwell time = 5+/-0.5sec MIL-STD-750 TM2026	15	Pass	15/15



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Qualification - Continued

No.	Test	Conditions (Reference standards are in bold)	Qty	Pass/Fail	Test Results
G	Helium Fine Leak Test	Pressurize 30 to 60 psi for 2 to 10 hours depending on package volume. MIL-STD-883 TM1014 condition A1	77	Pass	77/77
H	Gross Leak Test (Bubble Test)	Pressurize 75 psia (60 psi) for 2 hours. T= +125°C ±5°C. Immersion depth = 2" t= 1 minute minimum. MIL-STD-750 TM1071 condition C	77	Pass	77/77
I	Mechanical Shock	Peak acceleration = 1500G, t = 0.5 ms JESD22-B110 Table 1 condition B	15	Pass	15/15

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February 13, 2025

Sample Availability:

Please contact your salesperson or manufacturer's representative for samples.

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	